

SOT973-1

plastic thermal enhanced extremely thin small outline
package; no leads; 12 terminals; body 1.35 x 2.5 x 0.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HXSON12
Package type industry code	HXSON12
Package style descriptive code	HXSON (thermal enhanced extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	13-11-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.4	-	2.5	2.6	mm
E	package width		1.25	-	1.35	1.45	mm
A	seated height		[tbd]	-	[tbd]	0.5	mm
e	nominal pitch		-	-	0.4	-	mm
n ₂	actual quantity of termination		-	-	12	-	



plastic thermal enhanced extremely thin small
outline package; no leads; 12 terminals; body
1.35 x 2.5 x 0.5 mm

2. Package outline

HXSON12: plastic thermal enhanced extremely thin small outline package; no leads;
12 terminals; body 1.35 x 2.5 x 0.5 mm

SOT973-1

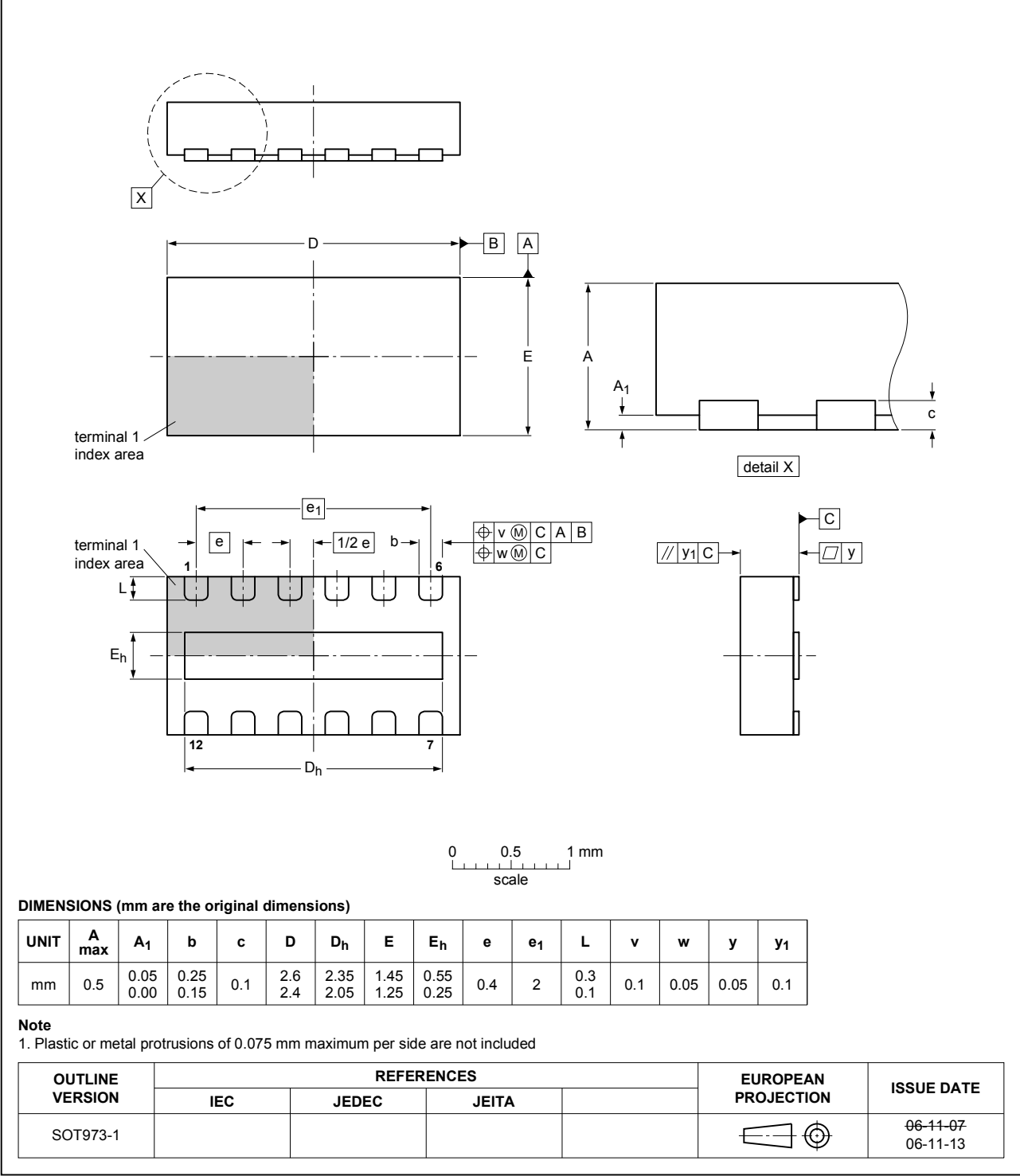


Fig. 1. Package outline HXSON12 (SOT973-1)

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3. Legal information

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